

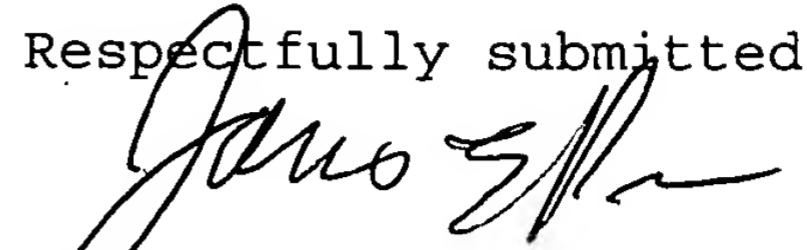
REMARKS

Claims 51, 58, and 65 are amended to correct omissions related to the "die paddle" in each of those claims. In particular, claim 51 is amended to include that the semiconductor die is mounted on the die paddle (see claim 65 and e.g. Fig. 3B.). Claims 58 and 65 are amended to include an antecedent for the term "the die paddle," which subsequently is used in the claims. Claim 65 also is amended to delete the term "by an adhesive layer," so as to be consistent with the other independent claims.

These amendments do not introduce new matter, as all are well supported in the application, e.g., Fig. 3B, and in the claims themselves. Further, it is not anticipated that this amendment will in anyway upset the Examiner's conclusions of patentability, and will not require further searching by the Examiner.

Please direct any comments or questions to the
undersigned at 408 451-5906.

Respectfully submitted,


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I hereby certify that this correspondence is being deposited with the United States Postal Service as FIRST CLASS MAIL in an envelope addressed to Mail Stop Issue Fee, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on March 29, 2004.

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